

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT4709705

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HIDEYUKI SAWAI	10/30/2017
MASAKAZU SUGIURA	10/30/2017
RECEIVING PARTY DATA	
Name:	SII SEMICONDUCTOR CORPORATION
Street Address:	8, NAKASE 1-CHOME, MIHAMA-KU
City:	CHIBA-SHI, CHIBA
State/Country:	JAPAN
Postal Code:	261-8507
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15826047
CORRESPONDENCE DATA	
Fax Number:	(312)321-4299
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	312-321-4200
Email:	khinokawa@brinksgilson.com, usassignments@brinksgilson.com
Correspondent Name:	TADASHI HORIE/KOH HINOKAWA
Address Line 1:	P.O. BOX 10395
Address Line 4:	CHICAGO, ILLINOIS 60610
ATTORNEY DOCKET NUMBER:	11106/993
NAME OF SUBMITTER:	TADASHI HORIE
SIGNATURE:	/Tadashi Horie/
DATE SIGNED:	11/29/2017
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, Hideyuki SAWAI and Masakazu SUGIURA, hereinafter called the "Assignors", have made the invention described in the United States patent application entitled LEVEL SHIFT CIRCUIT, executed by Assignors on the same date as, or on a date prior to, this Assignment;

WHEREAS, SII Semiconductor Corporation, a corporation organized and existing under the laws of Japan, having a place of business at 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, Japan 261-8507, hereinafter called the "Assignee", desires to acquire the entire right, title and interest in and to the invention and the patent application identified above, and all patents which may be obtained for said invention, as set forth below;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other valuable and legally sufficient consideration, the receipt of which by the Assignors from the Assignee is hereby acknowledged, the Assignors have sold, assigned and transferred, and by these presents do sell, assign and transfer to the Assignee, the entire right, title and interest for the United States in and to the invention and the patent application identified above, and any patents that may issue for said invention in the United States; together with the entire right, title and interest in and to said invention and all patent applications and patents therefor in all countries foreign to the United States, including the full right to claim for any such application all benefits and priority rights under any applicable convention; together with the entire right, title and interest in and to all continuations, divisions, renewals and extensions of any of the patent applications and patents defined above; to have and to hold for the sole and exclusive use and benefit of the Assignee, its successors and assigns, to the full end of the term or terms for all such patents.

The Assignors hereby covenant and agree, for both the Assignors and the Assignors' legal representatives, that the Assignors will assist the Assignee in the prosecution of the patent application identified above; in the making and prosecution of any other patent applications that the Assignee may elect to make covering the invention identified above; in vesting in the Assignee like exclusive title in and to all such other patent applications and patents; and in the prosecution of any interference which may arise involving said invention, or any such patent application or patent; and that the Assignors will execute and deliver to the Assignee any and all additional papers which may be requested by the Assignee to carry out the terms of this Assignment.

The Commissioner of Patents and Trademarks is hereby authorized and requested to issue patents to the Assignee in accordance with the terms of this Assignment.

IN TESTIMONY WHEREOF, the Assignors have executed this agreement.

DATE: 2017.10.30 Hideyuki SAWAI
Hideyuki SAWAI

WITNESSED:

DATE: _____

DATE: _____

DATE: 2017.10.30 Masakazu SUGIURA
Masakazu SUGIURA

WITNESSED:

DATE: _____

DATE: _____